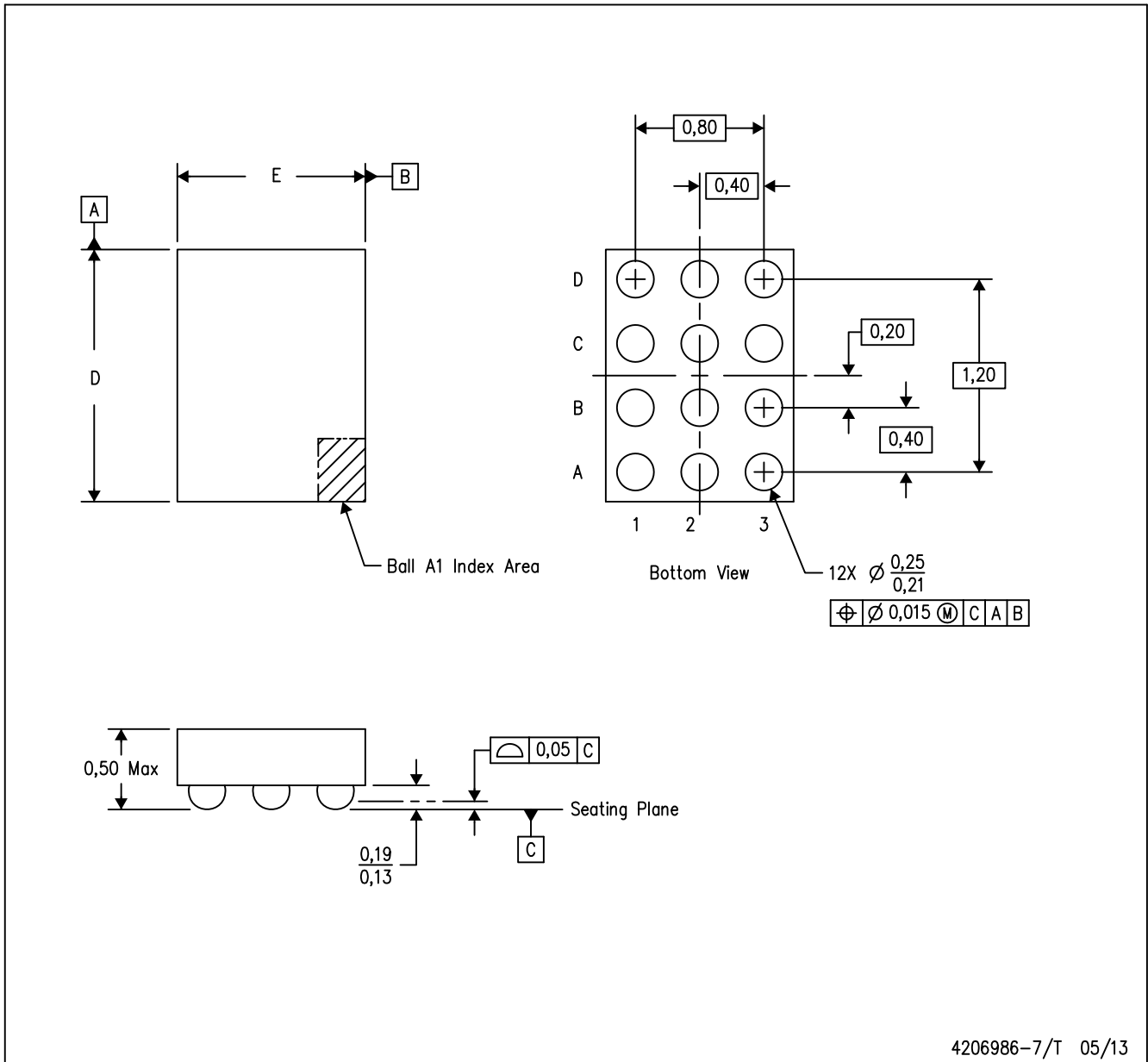


YFP (R-XBGA-N12)

DIE-SIZE BALL GRID ARRAY



4206986-7/T 05/13

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

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